

# 74HC574; 74HCT574

Octal D-type flip-flop; positive edge-trigger; 3-state

Rev. 7 — 4 March 2016

Product data sheet

## 1. General description

The 74HC574; 74HCT574 is an 8-bit positive-edge triggered D-type flip-flop with 3-state outputs. The device features a clock (CP) and output enable ( $\overline{OE}$ ) inputs. The flip-flops will store the state of their individual D-inputs that meet the set-up and hold time requirements on the LOW-to-HIGH clock (CP) transition. A HIGH on  $\overline{OE}$  causes the outputs to assume a high-impedance OFF-state. Operation of the  $\overline{OE}$  input does not affect the state of the flip-flops. Inputs include clamp diodes. This enables the use of current limiting resistors to interface inputs to voltages in excess of  $V_{CC}$ .

## 2. Features and benefits

- Input levels:
  - ◆ For 74HC574: CMOS level
  - ◆ For 74HCT574: TTL level
- 3-state non-inverting outputs for bus oriented applications
- 8-bit positive, edge-triggered register
- Common 3-state output enable input
- Complies with JEDEC standard no. 7 A
- Multiple package options
- ESD protection:
  - ◆ HBM JESD22-A114F exceeds 2 000 V
  - ◆ MM JESD22-A115-A exceeds 200 V
- Specified from  $-40\text{ }^{\circ}\text{C}$  to  $+85\text{ }^{\circ}\text{C}$  and from  $-40\text{ }^{\circ}\text{C}$  to  $+125\text{ }^{\circ}\text{C}$

## 3. Ordering information

Table 1. Ordering information

Type number	Package			
	Temperature range	Name	Description	Version
74HC574D	$-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$	SO20	plastic small outline package; 20 leads; body width 7.5 mm	SOT163-1
74HCT574D				
74HC574DB	$-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$	SSOP20	plastic shrink small outline package; 20 leads; body width 5.3 mm	SOT339-1
74HCT574DB				
74HC574PW	$-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$	TSSOP20	plastic thin shrink small outline package; 20 leads; body width 4.4 mm	SOT360-1
74HCT574PW				



## 4. Functional diagram



Fig 1. Functional diagram



Fig 2. Logic diagram

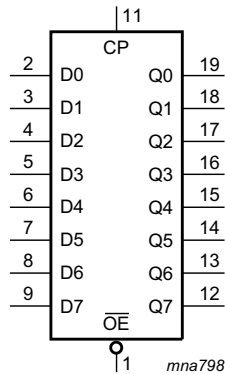


Fig 3. Logic symbol

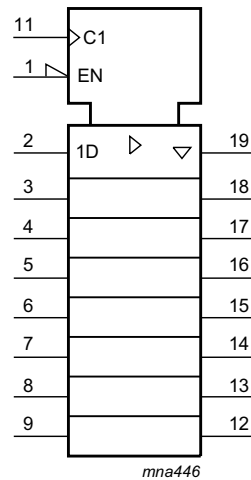


Fig 4. IEC logic symbol

## 5. Pinning information

### 5.1 Pinning

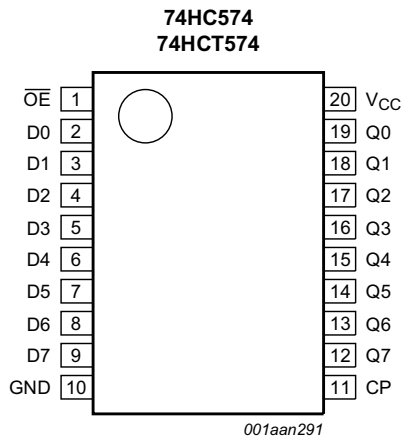


Fig 5. Pin configuration SO20, SSOP20 and TSSOP20

### 5.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
$\overline{OE}$	1	3-state output enable input (active LOW)
D[0:7]	2, 3, 4, 5, 6, 7, 8, 9	data input
GND	10	ground (0 V)
CP	11	clock input (LOW-to-HIGH, edge triggered)
Q[0:7]	19, 18, 17, 16, 15, 14, 13, 12	3-state flip-flop output
V <sub>CC</sub>	20	supply voltage

## 6. Functional description

Table 3. Function table<sup>[1]</sup>

Operating mode	Input			Internal flip-flop	Output
	$\overline{\text{OE}}$	CP	Dn		Qn
Load and read register	L	↑	l	L	L
	L	↑	h	H	H
Load register and disable output	H	↑	l	L	Z
	H	↑	h	H	Z

- [1] H = HIGH voltage level;  
 h = HIGH voltage level one setup time prior to the HIGH-to-LOW CP transition;  
 L = LOW voltage level;  
 l = LOW voltage level one setup time prior to the HIGH-to-LOW CP transition;  
 Z = high-impedance OFF-state;  
 ↑ = LOW-to-HIGH clock transition.

## 7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{CC}$	supply voltage		-0.5	+7	V
$I_{IK}$	input clamping current	$V_I < -0.5 \text{ V}$ or $V_I > V_{CC} + 0.5 \text{ V}$	-	±20	mA
$I_{OK}$	output clamping current	$V_O < -0.5 \text{ V}$ or $V_O > V_{CC} + 0.5 \text{ V}$	-	±20	mA
$I_O$	output current	$V_O = -0.5 \text{ V}$ to $(V_{CC} + 0.5 \text{ V})$	-	±35	mA
$I_{CC}$	supply current		-	+70	mA
$I_{GND}$	ground current		-	-70	mA
$T_{stg}$	storage temperature		-65	+150	°C
$P_{tot}$	total power dissipation	SO20, SSOP20 and TSSOP20 packages <sup>[1]</sup>	-	500	mW

- [1] For SO20:  $P_{tot}$  derates linearly with 8 mW/K above 70 °C.  
 For SSOP20 and TSSOP20 packages:  $P_{tot}$  derates linearly with 5.5 mW/K above 60 °C.

## 8. Recommended operating conditions

Table 5. Recommended operating conditions

Voltages are referenced to GND (ground = 0 V)

Symbol	Parameter	Conditions	74HC574			74HCT574			Unit
			Min	Typ	Max	Min	Typ	Max	
$V_{CC}$	supply voltage		2.0	5.0	6.0	4.5	5.0	5.5	V
$V_I$	input voltage		0	-	$V_{CC}$	0	-	$V_{CC}$	V
$V_O$	output voltage		0	-	$V_{CC}$	0	-	$V_{CC}$	V
$T_{amb}$	ambient temperature		-40	+25	+125	-40	+25	+125	°C

**Table 5. Recommended operating conditions ...continued**  
 Voltages are referenced to GND (ground = 0 V) ...continued

Symbol	Parameter	Conditions	74HC574			74HCT574			Unit
			Min	Typ	Max	Min	Typ	Max	
$\Delta t/\Delta V$	input transition rise and fall rate	$V_{CC} = 2.0\text{ V}$	-	-	625	-	-	-	ns/V
		$V_{CC} = 4.5\text{ V}$	-	1.67	139	-	1.67	139	ns/V
		$V_{CC} = 6.0\text{ V}$	-	-	83	-	-	-	ns/V

## 9. Static characteristics

**Table 6. Static characteristics**

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
<b>74HC574</b>										
$V_{IH}$	HIGH-level input voltage	$V_{CC} = 2.0\text{ V}$	1.5	1.2	-	1.5	-	1.5	-	V
		$V_{CC} = 4.5\text{ V}$	3.15	2.4	-	3.15	-	3.15	-	V
		$V_{CC} = 6.0\text{ V}$	4.2	3.2	-	4.2	-	4.2	-	V
$V_{IL}$	LOW-level input voltage	$V_{CC} = 2.0\text{ V}$	-	0.8	0.5	-	0.5	-	0.5	V
		$V_{CC} = 4.5\text{ V}$	-	2.1	1.35	-	1.35	-	1.35	V
		$V_{CC} = 6.0\text{ V}$	-	2.8	1.8	-	1.8	-	1.8	V
$V_{OH}$	HIGH-level output voltage	$V_I = V_{IH}$ or $V_{IL}$								
		$I_O = -20\ \mu\text{A}; V_{CC} = 2.0\text{ V}$	1.9	2.0	-	1.9	-	1.9	-	V
		$I_O = -20\ \mu\text{A}; V_{CC} = 4.5\text{ V}$	4.4	4.5	-	4.4	-	4.4	-	V
		$I_O = -20\ \mu\text{A}; V_{CC} = 6.0\text{ V}$	5.9	6.0	-	5.9	-	5.9	-	V
		$I_O = -6.0\text{ mA}; V_{CC} = 4.5\text{ V}$	3.98	4.32	-	3.84	-	3.7	-	V
		$I_O = -7.8\text{ mA}; V_{CC} = 6.0\text{ V}$	5.48	5.81	-	5.34	-	5.2	-	V
$V_{OL}$	LOW-level output voltage	$V_I = V_{IH}$ or $V_{IL}$								
		$I_O = 20\ \mu\text{A}; V_{CC} = 2.0\text{ V}$	-	0	0.1	-	0.1	-	0.1	V
		$I_O = 20\ \mu\text{A}; V_{CC} = 4.5\text{ V}$	-	0	0.1	-	0.1	-	0.1	V
		$I_O = 20\ \mu\text{A}; V_{CC} = 6.0\text{ V}$	-	0	0.1	-	0.1	-	0.1	V
		$I_O = 6.0\text{ mA}; V_{CC} = 4.5\text{ V}$	-	0.15	0.26	-	0.33	-	0.4	V
		$I_O = 7.8\text{ mA}; V_{CC} = 6.0\text{ V}$	-	0.16	0.26	-	0.33	-	0.4	V
$I_I$	input leakage current	$V_I = V_{CC}$ or GND; $V_{CC} = 6.0\text{ V}$	-	-	$\pm 0.1$	-	$\pm 1.0$	-	$\pm 1.0$	$\mu\text{A}$
$I_{OZ}$	OFF-state output current	$V_I = V_{IH}$ or $V_{IL}; V_{CC} = 6.0\text{ V};$ $V_O = V_{CC}$ or GND	-	-	$\pm 0.5$	-	$\pm 5.0$	-	$\pm 10.0$	$\mu\text{A}$
$I_{CC}$	supply current	$V_I = V_{CC}$ or GND; $I_O = 0\text{ A};$ $V_{CC} = 6.0\text{ V}$	-	-	8.0	-	80	-	160	$\mu\text{A}$
$C_I$	input capacitance		-	3.5	-	-	-	-	-	pF

**Table 6. Static characteristics ...continued**

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
<b>74HCT574</b>										
V <sub>IH</sub>	HIGH-level input voltage	V <sub>CC</sub> = 4.5 V to 5.5 V	2.0	1.6	-	2.0	-	2.0	-	V
V <sub>IL</sub>	LOW-level input voltage	V <sub>CC</sub> = 4.5 V to 5.5 V	-	1.2	0.8	-	0.8	-	0.8	V
V <sub>OH</sub>	HIGH-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; V <sub>CC</sub> = 4.5 V								
		I <sub>O</sub> = -20 μA	4.4	4.5	-	4.4	-	4.4	-	V
		I <sub>O</sub> = -6 mA	3.98	4.32	-	3.84	-	3.7	-	V
V <sub>OL</sub>	LOW-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; V <sub>CC</sub> = 4.5 V								
		I <sub>O</sub> = 20 μA	-	0	0.1	-	0.1	-	0.1	V
		I <sub>O</sub> = 6.0 mA	-	0.16	0.26	-	0.33	-	0.4	V
I <sub>I</sub>	input leakage current	V <sub>I</sub> = V <sub>CC</sub> or GND; V <sub>CC</sub> = 5.5 V	-	-	±0.1	-	±1.0	-	±1.0	μA
I <sub>OZ</sub>	OFF-state output current	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; V <sub>CC</sub> = 5.5 V; V <sub>O</sub> = V <sub>CC</sub> or GND	-	-	±0.5	-	±5.0	-	±10	μA
I <sub>CC</sub>	supply current	V <sub>I</sub> = V <sub>CC</sub> or GND; I <sub>O</sub> = 0 A; V <sub>CC</sub> = 5.5 V	-	-	8.0	-	80	-	160	μA
ΔI <sub>CC</sub>	additional supply current	V <sub>I</sub> = V <sub>CC</sub> - 2.1 V; other inputs at V <sub>CC</sub> or GND; V <sub>CC</sub> = 4.5 V to 5.5 V; I <sub>O</sub> = 0 A								
		per input pin; Dn inputs	-	50	180	-	225	-	245	μA
		per input pin; $\overline{OE}$ input	-	125	450	-	563	-	613	μA
		per input pin; CP input	-	150	540	-	675	-	735	μA
C <sub>I</sub>	input capacitance		-	3.5	-	-	-	-	-	pF

## 10. Dynamic characteristics

**Table 7. Dynamic characteristics**

Voltages are referenced to GND (ground = 0 V);  $C_L = 50$  pF unless otherwise specified; for test circuit see [Figure 9](#).

Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
<b>74HC574</b>										
$t_{pd}$	propagation delay	CP to Qn; see <a href="#">Figure 6</a> [1]								
		$V_{CC} = 2.0$ V	-	47	150	-	190	-	225	ns
		$V_{CC} = 4.5$ V	-	17	30	-	35	-	45	ns
		$V_{CC} = 5$ V; $C_L = 15$ pF	-	14	-	-	-	-	-	ns
		$V_{CC} = 6.0$ V	-	14	26	-	33	-	38	ns
$t_{en}$	enable time	OE to Qn; see <a href="#">Figure 8</a> [2]								
		$V_{CC} = 2.0$ V	-	44	140	-	175	-	210	ns
		$V_{CC} = 4.5$ V	-	16	28	-	35	-	42	ns
		$V_{CC} = 6.0$ V	-	13	24	-	30	-	36	ns
$t_{dis}$	disable time	OE to Qn; see <a href="#">Figure 8</a> [3]								
		$V_{CC} = 2.0$ V	-	39	125	-	155	-	190	ns
		$V_{CC} = 4.5$ V	-	14	25	-	31	-	38	ns
		$V_{CC} = 6.0$ V	-	11	21	-	26	-	32	ns
$t_t$	transition time	Qn; see <a href="#">Figure 6</a> [4]								
		$V_{CC} = 2.0$ V	-	14	60	-	75	-	90	ns
		$V_{CC} = 4.5$ V	-	5	12	-	15	-	18	ns
		$V_{CC} = 6.0$ V	-	4	10	-	13	-	15	ns
$t_W$	pulse width	CP HIGH or LOW; see <a href="#">Figure 7</a>								
		$V_{CC} = 2.0$ V	80	14	-	100	-	120	-	ns
		$V_{CC} = 4.5$ V	16	5	-	20	-	24	-	ns
		$V_{CC} = 6.0$ V	14	4	-	17	-	20	-	ns
$t_{su}$	set-up time	Dn to CP; see <a href="#">Figure 7</a>								
		$V_{CC} = 2.0$ V	60	6	-	75	-	90	-	ns
		$V_{CC} = 4.5$ V	12	2	-	15	-	18	-	ns
		$V_{CC} = 6.0$ V	10	2	-	13	-	15	-	ns
$t_h$	hold time	Dn to CP; see <a href="#">Figure 7</a>								
		$V_{CC} = 2.0$ V	5	0	-	5	-	5	-	ns
		$V_{CC} = 4.5$ V	5	0	-	5	-	5	-	ns
		$V_{CC} = 6.0$ V	5	0	-	5	-	5	-	ns
$f_{max}$	maximum frequency	CP; see <a href="#">Figure 6</a>								
		$V_{CC} = 2.0$ V	6.0	37	-	4.8	-	4.0	-	MHz
		$V_{CC} = 4.5$ V	30	112	-	24	-	20	-	MHz
		$V_{CC} = 5$ V; $C_L = 15$ pF	-	123	-	-	-	-	-	MHz
		$V_{CC} = 6.0$ V	35	133	-	28	-	24	-	MHz

**Table 7. Dynamic characteristics ...continued**

Voltages are referenced to GND (ground = 0 V);  $C_L = 50$  pF unless otherwise specified; for test circuit see [Figure 9](#).

Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
$C_{PD}$	power dissipation capacitance	$C_L = 50$ pF; $f = 1$ MHz; $V_I = \text{GND to } V_{CC}$ [5]	-	22	-	-	-	-	-	pF
<b>74HCT574</b>										
$t_{pd}$	propagation delay	CP to Qn; see <a href="#">Figure 6</a> [1]								
		$V_{CC} = 4.5$ V	-	18	33	-	41	-	50	ns
		$V_{CC} = 5$ V; $C_L = 15$ pF	-	15	-	-	-	-	-	ns
$t_{en}$	enable time	OE to Qn; see <a href="#">Figure 8</a> [2]								
		$V_{CC} = 4.5$ V	-	19	33	-	41	-	50	ns
$t_{dis}$	disable time	OE to Qn; see <a href="#">Figure 8</a> [3]								
		$V_{CC} = 4.5$ V	-	16	28	-	35	-	42	ns
$t_t$	transition time	Qn; see <a href="#">Figure 6</a> [4]								
		$V_{CC} = 4.5$ V	-	5	12	-	15	-	18	ns
$t_W$	pulse width	CP HIGH or LOW; see <a href="#">Figure 7</a>								
		$V_{CC} = 4.5$ V	16	7	-	20	-	24	-	ns
$t_{su}$	set-up time	Dn to CP; see <a href="#">Figure 7</a>								
		$V_{CC} = 4.5$ V	12	3	-	15	-	18	-	ns
$t_h$	hold time	Dn to CP; see <a href="#">Figure 7</a>								
		$V_{CC} = 4.5$ V	5	-1	-	5	-	5	-	ns
$f_{max}$	maximum frequency	CP; see <a href="#">Figure 6</a>								
		$V_{CC} = 4.5$ V	30	69	-	24	-	20	-	MHz
		$V_{CC} = 5$ V; $C_L = 15$ pF	-	76	-	-	-	-	-	MHz
$C_{PD}$	power dissipation capacitance	$C_L = 50$ pF; $f = 1$ MHz; $V_I = \text{GND to } V_{CC} - 1.5$ V [5]	-	25	-	-	-	-	-	pF

- [1]  $t_{pd}$  is the same as  $t_{PLH}$  and  $t_{PHL}$ .
- [2]  $t_{en}$  is the same as  $t_{PZH}$  and  $t_{PZL}$ .
- [3]  $t_{dis}$  is the same as  $t_{PLZ}$  and  $t_{PHZ}$ .
- [4]  $t_t$  is the same as  $t_{THL}$  and  $t_{TLH}$ .
- [5]  $C_{PD}$  is used to determine the dynamic power dissipation ( $P_D$  in  $\mu\text{W}$ ).  
 $P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \sum(C_L \times V_{CC}^2 \times f_o)$  where:  
 $f_i$  = input frequency in MHz;  
 $f_o$  = output frequency in MHz;  
 $C_L$  = output load capacitance in pF;  
 $V_{CC}$  = supply voltage in V;  
 $N$  = number of inputs switching;  
 $\sum(C_L \times V_{CC}^2 \times f_o)$  = sum of outputs.



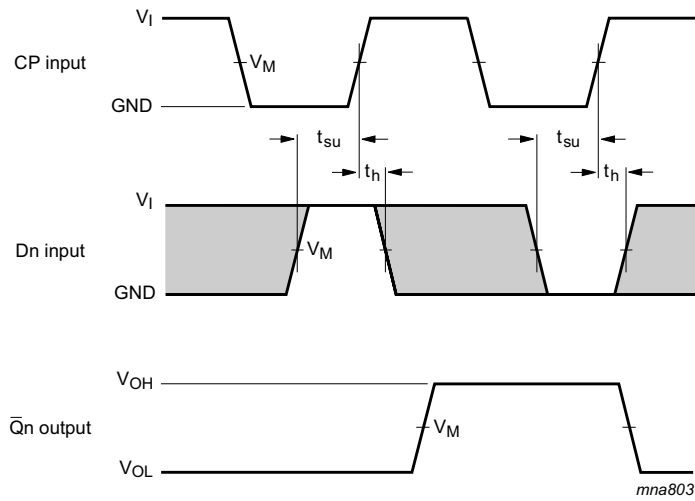
11. Waveforms



Measurement points are given in [Table 8](#).

$V_{OL}$  and  $V_{OH}$  are typical voltage output levels that occur with the output load.

**Fig 6. Propagation delay input (CP) to output (Qn), output transition time, clock input (CP) pulse width and the maximum frequency (CP)**



Measurement points are given in [Table 8](#).

$V_{OL}$  and  $V_{OH}$  are typical voltage output levels that occur with the output load.

**Fig 7. The data input (D) to clock input (CP) set-up times and clock input (CP) to data input (D) hold times**



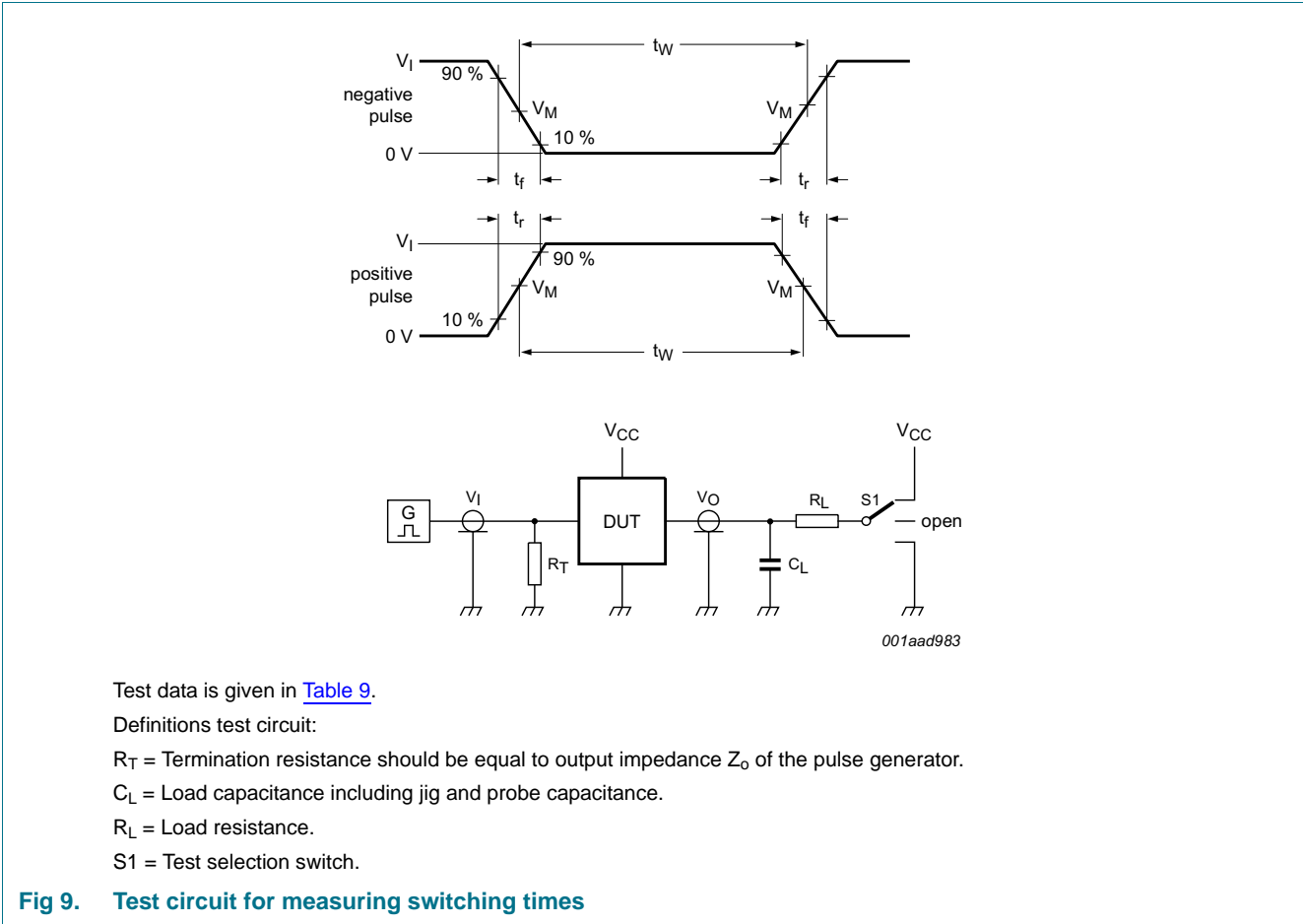
Measurement points are given in [Table 8](#).

$V_{OL}$  and  $V_{OH}$  are typical voltage output levels that occur with the output load.

**Fig 8. Enable and disable times**

**Table 8. Measurement points**

Type	Input	Output		
	$V_M$	$V_M$	$V_X$	$V_Y$
74HC574	$0.5V_{CC}$	$0.5V_{CC}$	$0.1V_{CC}$	$0.9V_{CC}$
74HCT574	1.3 V	1.3 V	$0.1V_{CC}$	$0.9V_{CC}$



**Table 9. Test data**

Type	Input		Load		S1 position		
	$V_I$	$t_r, t_f$	$C_L$	$R_L$	$t_{PHL}, t_{PLH}$	$t_{PZH}, t_{PHZ}$	$t_{PZL}, t_{PLZ}$
74HC574	$V_{CC}$	6 ns	15 pF, 50 pF	1 k $\Omega$	open	GND	$V_{CC}$
74HCT574	3 V	6 ns	15 pF, 50 pF	1 k $\Omega$	open	GND	$V_{CC}$

12. Package outline

SO20: plastic small outline package; 20 leads; body width 7.5 mm

SOT163-1



Fig 10. Package outline SOT163-1 (SO20)

SSOP20: plastic shrink small outline package; 20 leads; body width 5.3 mm

SOT339-1



Fig 11. Package outline SOT339-1 (SSOP20)

TSSOP20: plastic thin shrink small outline package; 20 leads; body width 4.4 mm

SOT360-1

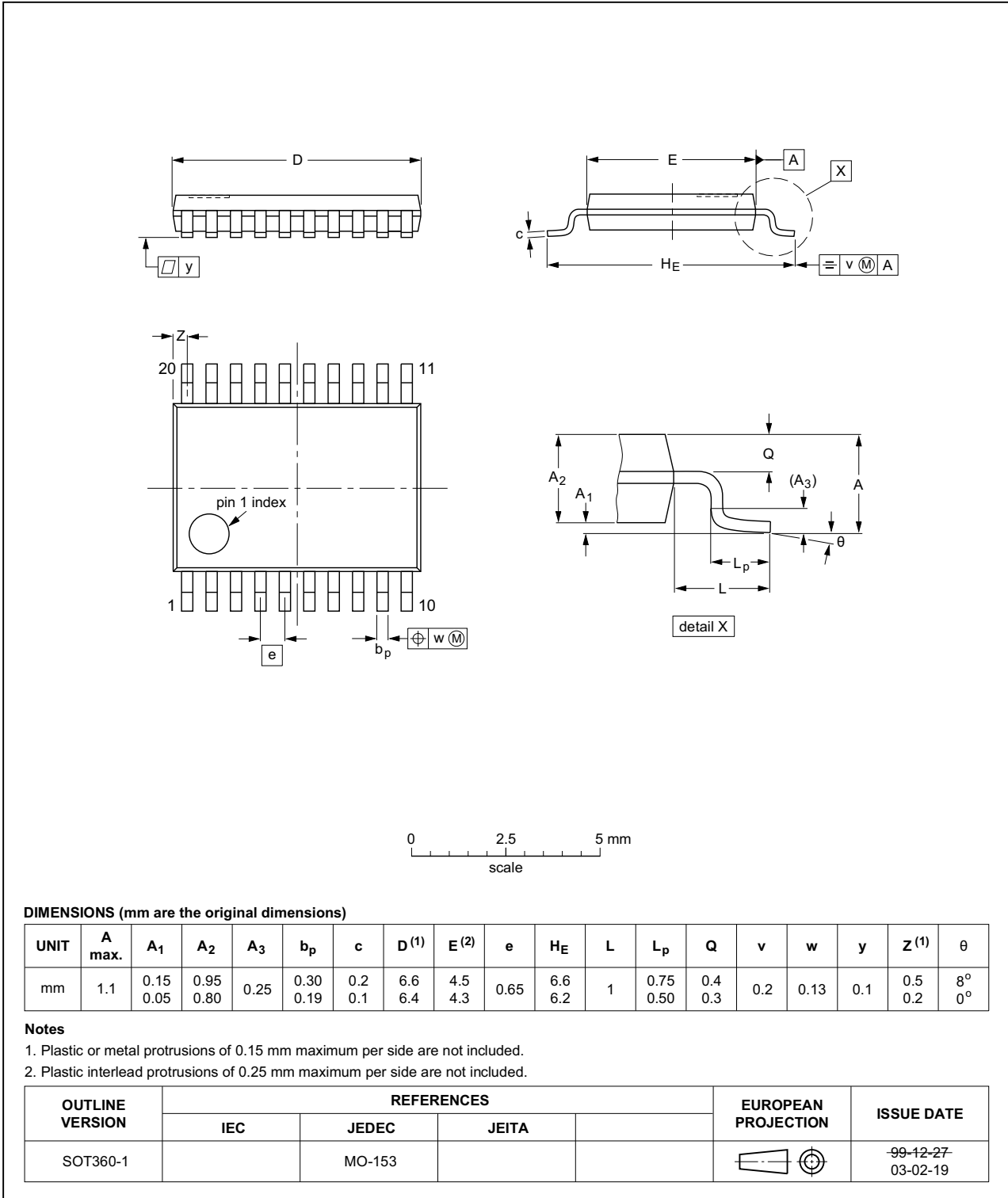


Fig 12. Package outline SOT360-1 (TSSOP20)

## 13. Abbreviations

Table 10. Abbreviations

Acronym	Description
CMOS	Complementary Metal Oxide Semiconductor
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
MM	Machine Model
TTL	Transistor-Transistor Logic

## 14. Revision history

Table 11. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74HC_HCT574 v.7	20160304	Product data sheet	-	74HC_HCT574 v.6
Modifications:	<ul style="list-style-type: none"> <li>Type numbers 74HC574N and 74HCT574N (SOT146-1) removed.</li> </ul>			
74HC_HCT574 v.6	20150126	Product data sheet	-	74HC_HCT574 v.5
Modifications:	<ul style="list-style-type: none"> <li><a href="#">Table 7</a>: Power dissipation capacitance condition for 74HCT574 is corrected.</li> </ul>			
74HC_HCT574 v.5	20120425	Product data sheet	-	74HC_HCT574 v.4
Modifications:	<ul style="list-style-type: none"> <li><math>V_X</math> and <math>V_Y</math> measurement points added to Table 8.</li> </ul>			
74HC_HCT574 v.4	20111219	Product data sheet	-	74HC_HCT574 v.3
Modifications:	<ul style="list-style-type: none"> <li>Legal pages updated.</li> </ul>			
74HC_HCT574 v.3	20101215	Product data sheet	-	74HC_HCT574_CNV v.2
74HC_HCT574_CNV v.2	19970827	Product specification	-	-

## 15. Legal information

### 15.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

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